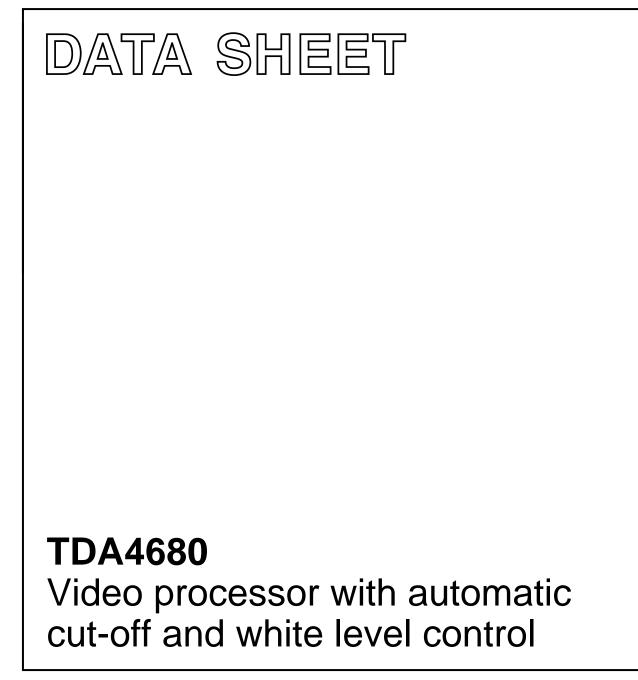
INTEGRATED CIRCUITS



Product specification Supersedes data of April 1993 File under Integrated Circuits, IC02 1996 Oct 25



TDA4680

Video processor with automatic cut-off and white level control

FEATURES

- Operates from an 8 V DC supply
- Black level clamping of the colour difference, luminance and RGB input signals with coupling-capacitor DC level storage
- Two fully-controlled, analog RGB inputs, selected either by fast switch signals or via I²C-bus
- Saturation, contrast and brightness adjustment via l²C-bus
- Same RGB output black levels for Y/CD and RGB input signals
- Timing pulse generation from either a 2 or 3-level sandcastle pulse for clamping, horizontal and vertical synchronization, cut-off and white level timing pulses
- Automatic cut-off control with picture tube leakage current compensation
- Software-based automatic white level control or fixed white levels via I²C-bus
- Cut-off and white level measurement pulses in the last 4 lines of the vertical blanking interval (I²C-bus selection for PAL, SECAM, or NTSC, PAL-M)
- Increased RGB signal bandwidths for progressive scan and 100 Hz operation (selected via I²C-bus)
- Two switch-on delays to prevent discolouration before steady-state operation
- · Average beam current and peak drive limiting
- PAL/SECAM or NTSC matrix selection via I²C-bus
- Three adjustable reference voltage levels (via I²C-bus) for automatic cut-off and white level control
- Emitter-follower RGB output stages to drive the video output stages
- Hue control output for the TDA4555, TDA4650/T, TDA4655/T or TDA4657.



GENERAL DESCRIPTION

The TDA4680 is a monolithic integrated circuit with a colour difference interface for video processing in TV receivers. Its primary function is to process the luminance and colour difference signals from multistandard colour decoders, TDA4555, TDA4650/T, TDA4655/T or TDA4657, Colour Transient Improvement (CTI) IC, TDA4565, Picture Signal Improvement (PSI) IC, TDA4670, or from a feature module.

The required input signals are:

- · Luminance and negative colour difference signals
- 2 or 3-level sandcastle pulse for internal timing pulse generation
- I²C-bus data and clock signals for microcontroller control.

Two sets of analog RGB colour signals can also be inserted, e.g. one from a peritelevision connector and the other from an on-screen display generator; both inputs are fully-controlled internally. The TDA4680 includes full I²C-bus control of all parameters and functions with automatic cut-off and white level control of the picture tube cathode currents. It provides RGB output signals for the video output stages.

There is a very similar IC TDA4681 available. The only differences are in the NTSC matrix.

TYPE NUMBER		PACKAGE					
ITPE NUMBER	NAME	DESCRIPTION	VERSION				
TDA4680	DIP28	plastic dual in-line package; 28 leads (600 mil)	SOT117-1				
TDA4680WP	PLCC28	plastic leaded chip carrier; 28 leads	SOT261-2				

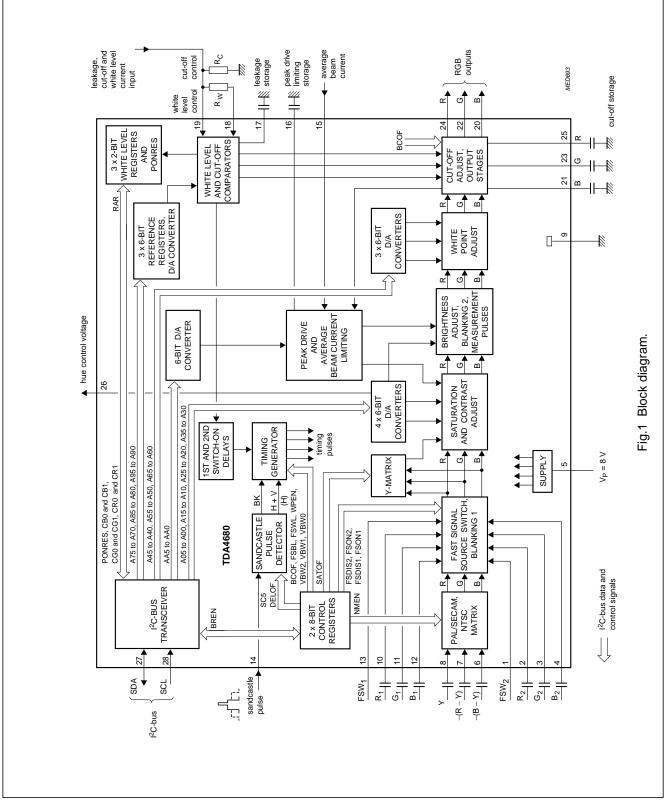
ORDERING INFORMATION

TDA4680

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VP	supply voltage (pin 5)	7.2	8.0	8.8	V
I _P	supply current (pin 5)	-	85	_	mA
V _{8(p-p)}	luminance input (peak-to-peak value)	-	0.45	-	V
V _{6(p-p)}	–(B – Y) input (peak-to-peak value)	-	1.33	_	V
V _{7(p-p)}	–(R – Y) input (peak-to-peak value)	-	1.05	-	V
V ₁₄	3-level sandcastle pulse				
	H + V	-	2.5	_	V
	Н	-	4.5	_	V
	BK	-	8.0	-	V
	2-level sandcastle pulse				
	H + V	-	2.5	_	V
	BK	_	4.5	_	V
V _{i(p-p)}	RGB input signals at pins 2, 3, 4, 10, 11 and 12 (peak-to-peak value)	-	0.7	_	V
V _{o(b-w)}	RGB outputs at pins 24, 22 and 20 (black-to-white value)	-	2.0	-	V
T _{amb}	operating ambient temperature	0	-	70	°C

BLOCK DIAGRAM

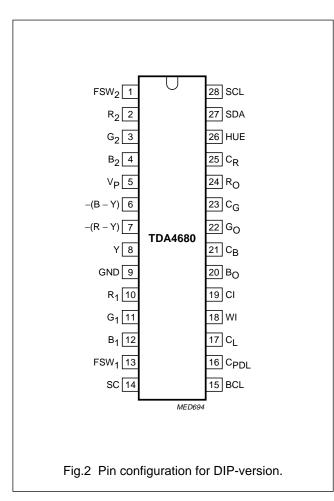


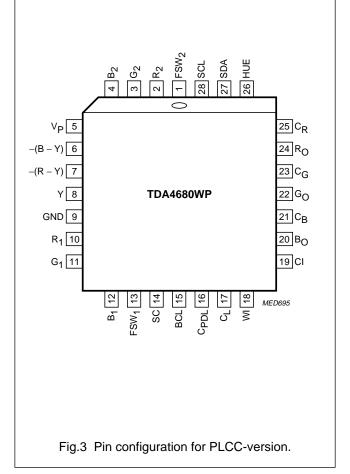
1996 Oct 25

PINNING

SYMBOL	PIN	DESCRIPTION
FSW ₂	1	fast switch 2 input
R ₂	2	red input 2
G ₂	3	green input 2
B ₂	4	blue input 2
VP	5	supply voltage
-(B - Y)	6	colour difference input –(B – Y)
-(R - Y)	7	colour difference input –(R – Y)
Υ	8	luminance input
GND	9	ground
R ₁	10	red input 1
G ₁	11	green input 1
B ₁	12	blue input 1
FSW ₁	13	fast switch 1 input
SC	14	sandcastle pulse input
BCL	15	average beam current limiting input

SYMBOL	PIN	DESCRIPTION
C _{PDL}	16	storage capacitor for peak drive limiting
CL	17	storage capacitor for leakage current
WI	18	white level measurement input
CI	19	cut-off measurement input
B _O	20	blue output
C _B	21	blue cut-off storage capacitor
G _O	22	green output
C _G	23	green cut-off storage capacitor
R _O	24	red output
C _R	25	red cut-off storage capacitor
HUE	26	hue control output
SDA	27	I ² C-bus serial data input/output
SCL	28	I ² C-bus serial clock input





TDA4680

I²C-BUS

Control

The I²C-bus transmitter/receiver provides the data bytes to select and adjust the following functions and parameters:

- Brightness adjust
- Saturation adjust
- Contrast adjust
- Hue control voltage
- RGB gain adjust
- RGB reference voltage levels
- Peak drive limiting
- Selection of the vertical blanking interval and measurement lines for cut-off and white level control according to transmission standard
- Selects either 3-level or 2-level (5 V) sandcastle pulse
- · Enables/disables input clamping pulse delay
- · Enables/disables white level control
- · Enables cut-off control; enables output clamping
- Enables/disables full screen white level
- Enables/disables full screen black level
- Selects either PAL/SECAM or NTSC matrix
- Enables saturation adjust; enables nominal saturation
- Enables/disables synchronization of the execution of I²C-bus commands with the vertical blanking interval
- Reads the result of the comparison of the nominal and actual RGB signal levels for automatic white level control.

I²C-bustransmitter/receiver and data transfer

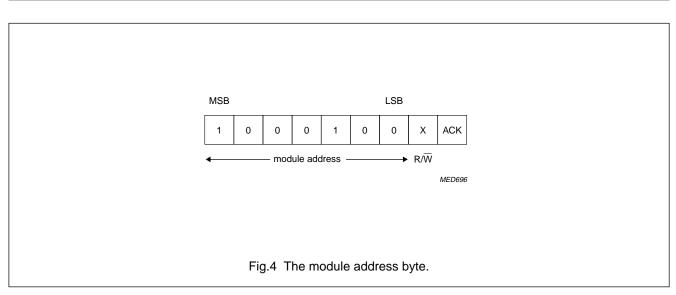
I²C-BUS SPECIFICATION

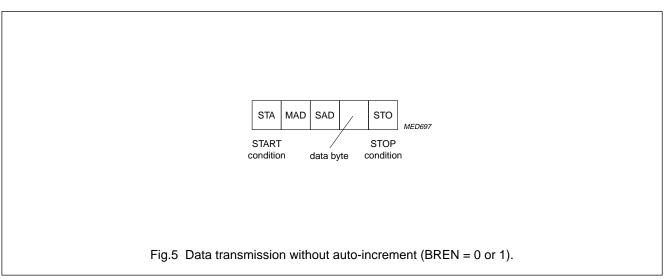
The I²C-bus is a bidirectional, two-wire, serial data bus for intercommunication between ICs in a system. The microcontroller transmits/receives data from the I²C-bus transceiver in the TDA4680 over the serial data line SDA (pin 27) synchronized by the serial clock line SCL (pin 28). Both lines are normally connected to a positive voltage supply through pull-up resistors. Data is transferred when the SCL line is LOW. When SCL is HIGH the serial data line SDA must be stable. A HIGH-to-LOW transition of the SDA line when SCL is HIGH is defined as a START bit. A LOW-to-HIGH transition of the SDA line when SCL is HIGH bit. Each transmission must start with a START bit and end with a STOP bit. The bus is busy after a START bit and is only free again after a STOP bit has been transmitted. I²C-BUS RECEIVER (MICROCONTROLLER WRITE MODE)

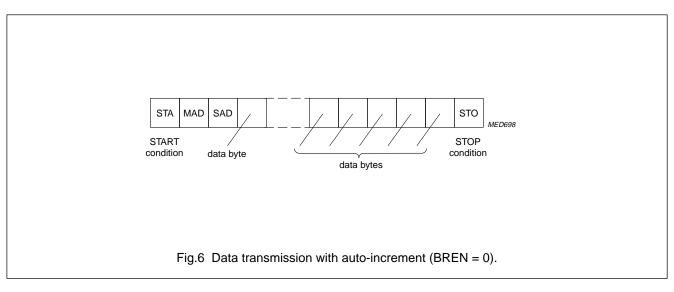
Each transmission to/from the I²C-bus transceiver consists of at least three bytes following the START bit. Each byte is acknowledged by an acknowledge bit immediately following each byte. The first byte is the Module Address (MAD) byte, also called slave address byte. This consists of the module address, 1000100 for the TDA4680, plus the R/W bit (see Fig.4). When the TDA4680 is a slave receiver (R/W = 0) the module address byte is 10001000 (88H). When the TDA4680 is a slave transmitter (R/W = 1) the module address byte is 10001001 (89H).

The length of a data transmission is unrestricted, but the module address and the correct sub-address must be transmitted before the data byte(s). The order of data transmission is shown in Figs 5 and 6. Without auto-increment (BREN = 0 or 1) the module address (MAD) byte is followed by a Sub-Address (SAD) byte and one data byte only (see Fig.5).

1996 Oct 25







AUTO-INCREMENT

The auto-increment format enables quick slave receiver initialization by one transmission, when the l^2C -bus control bit BREN = 0 (see control register bits of Table 1). If BREN = 1 auto-increment is not possible.

If the auto-increment format is selected, the MAD byte is followed by a SAD byte and by the data bytes of consecutive sub-addresses (Fig.6).

All sub-addresses from 00H to 0FH are automatically incremented, the sub-address counter wraps round from 0FH to 00H. Reserved sub-addresses 0BH, 0EH and 0FH are treated as legal but have no effect. Sub-addresses outside the range 00H and 0FH are not acknowledged by the device and neither auto-increment nor any other internal operation takes place (for versions V1 to V5 sub-addresses outside the range 00H and 0FH are acknowledged but neither auto-increment nor any other internal operation takes place).

Sub-addresses are stored in the TDA4680 to address the following parameters and functions (see Table 1):

- Brightness adjust
- Saturation adjust
- Contrast adjust
- Hue control voltage
- RGB gain adjust
- RGB reference voltage levels
- Peak drive limiting adjust
- Control register functions.

The data bytes D7 to D0 (see Table 1) provide the data of the parameters and functions for video processing.

CONTROL REGISTER 1

VBWx (Vertical Blanking Window):

x = 0, 1 or 2. VBWx selects the vertical blanking interval and positions the measurement lines for cut-off and white level control.

The actual lines in the vertical blanking interval after the start of the vertical pulses selected as measurement lines for cut-off and white level control are shown in Table 2.

The standards marked with (*) are for progressive line scan at double line frequency ($2f_L$), i.e. approximately 31 kHz.

NMEN (NTSC Matrix Enable):

- 0 = PAL/SECAM matrix
- 1 = NTSC matrix.

WPEN (White Pulse Enable):

- 0 = white measuring pulse disabled
- 1 = white measuring pulse enabled.

BREN (Buffer Register Enable):

0 = new data is executed as soon as it is received

1 = data is stored in buffer registers and is transferred to the data registers during the next vertical blanking interval.

The I²C-bus transceiver does not accept any new data until this data is transferred into the data registers.

DELOF (Delay Off) delays the leading edge of clamping pulses:

- 0 = delay enabled
- 1 = delay disabled.

SC5 (SandCastle 5 V):

- 0 = 3-level sandcastle pulse
- 1 = 2-level (5 V) sandcastle pulse.

CONTROL REGISTER 2

FSON2 (Fast Switch 2 ON)

- FSDIS2 (Fast Switch 2 Disable)
- FSON1 (Fast Switch 1 ON)
- FSDIS1 (Fast Switch 1 Disable)

The RGB input signals are selected by FSON2 and FSON1 or FSW₂ and FSW₁:

- FSON2 has priority over FSON1
- FSW₂ has priority over FSW₁
- FSDIS1 and FSDIS2 disable FSW₁ and FSW₂ (see Table 3).

BCOF (Black level Control Off):

0 = automatic cut-off control enabled

1 = automatic cut-off control disabled; RGB outputs are clamped to fixed DC levels.

FSBL (Full Screen Black Level):

0 = normal mode

1 = full screen black level (cut-off measurement level during full field).

- FSWL (Full Screen White Level):
 - 0 = normal mode

1 = full screen white level (white measurement level during full field).

SATOF (Saturation control Off):

0 = saturation control enabled

1 = saturation control disabled, nominal saturation enabled.

I²C-BUS TRANSMITTER (MICROCONTROLLER READ MODE)

As an I^2 C-bus transmitter, $R/\overline{W} = 1$, the TDA4680 sends a data byte from the status register to the microcontroller. The data byte consists of following bits: PONRES, CB1, CB0, CG1, CG0, CR1, CR0 and 0, where PONRES is the most significant bit.

PONRES (Power On Reset) monitors the state of TDA4680's supply voltage:

0 = normal operation

1 = supply voltage has dropped below approximately 6.0 V (usually occurs when the TV receiver is switched on or the supply voltage was interrupted).

When PONRES changes state from a logic LOW to a logic HIGH all data and function bits are set to logic LOW.

Table 1 Sub-address (SAD) and data bytes; note 1

2-BIT WHITE LEVEL	ERROR	SIGNAL	(see	Table 4)
		0.0.0.1	(000	

- CB1, CB0 = 2-bit white level of the blue channel.
- CG1, CG0 = 2-bit white level of the green channel.
- CR1, CR0 = 2-bit white level of the red channel.

MSB LSB SAD **FUNCTION** (HEX) D7 D3 D2 D1 D0 D6 D5 D4 00 0 A03 A02 **Brightness** 0 A05 A04 A01 A00 Saturation 01 0 0 A15 A14 A13 A12 A11 A10 Contrast 02 0 0 A25 A24 A23 A22 A21 A20 0 A33 A32 A31 Hue control voltage 03 0 A35 A34 A30 A45 A44 04 0 0 A43 A42 A41 A40 Red gain 0 05 0 A54 A53 A52 A51 A50 Green gain A55 06 0 0 A65 A64 A63 A62 A61 A60 Blue gain Red level reference 07 0 0 A75 A74 A73 A72 A71 A70 Green level reference 08 0 0 A85 A84 A83 A82 A81 A80 0 0 A92 A91 Blue level reference 09 A95 A94 A93 A90 Peak drive limit 0A 0 AA5 AA4 AA3 AA2 AA1 AA0 0 Reserved 0B Х Х Х Х Х Х Х Х Control register 1 0C SC5 DELOF BREN WPEN NMEN VBW2 VBW1 **VBW0** 0D SATOF FSWL **FSBL** BCOF FSDIS2 FSON2 FSDIS1 FSON1 Control register 2 Reserved 0E Х Х Х Х Х Х Х Х Reserved 0F Х Х Х Х Х Х Х Х

Note

1. X = don't care.



VBW2	VBW1	VBW0	R	G	В	WHITE	STANDARD
0	0	0	19	20	21	22	PAL/SECAM
0	0	1	16	17	18	19	NTSC/PAL M
0	1	0	22	23	24	25	PAL/SECAM (EB)
1	0	0	38, 39	40, 41	42, 43	44, 45	PAL*/SECAM*
1	0	1	32, 33	34, 35	36, 37	38, 39	NTSC*/PAL M*
1	1	0	44, 45	46, 47	48, 49	50, 51	PAL*/SECAM* (EB)

Table 2 Cut-off and white level measurement lines; notes 1 to 3

Notes

- 1. The line numbers given are those of the horizontal pulse counts after the start of the vertical component of the sandcastle pulse.
- 2. * line frequency of approximately 31 kHz.
- 3. (EB) is extended blanking.

I ² C	-BUS CO	NTROL E	BITS	ANALOG SWI	TCH SIGNALS	IN	D	
FSON2	FSDIS2	FSON1	FSDIS1	FSW ₂ (PIN 1)	FSW ₁ (PIN 13)	RGB ₂	RGB₁	Y/CD
L	L	L	L	L	L			ON
				L	Н		ON	
				Н	Х	ON		
L	L	L	Н	L	Х			ON
				Н	Х	ON		
L	L	Н	Х	L	Х		ON	
				Н	Х	ON		
L	н	L	L	Х	L			ON
				Х	Н		ON	
L	Н	L	Н	Х	Х			ON
L	Н	Н	Х	Х	Х		ON	
Н	Х	Х	Х	Х	Х	ON		

Notes

- 1. H: logical HIGH implies that the voltage >0.9 V.
- 2. L: logical LOW implies that the voltage <0.4 V.
- 3. X = don't care.
- 4. ON indicates the selected input signal.

Product specification

TDA4680

CX1	CX0	INTERPRETATION
0	0	RAR (Reset-After-Read): no new measurements since last read
1	0	actual (measured) white level less than the tolerance range
1	1	actual (measured) white level within the tolerance range
0	1	actual (measured) white level greater than the tolerance range

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _P	supply voltage (pin 5)	_	8.8	V
V _i	input voltage (pins 1 to 8, 10 to 13, 16, 21, 23 and 25)	-0.1	+V _P	V
	input voltage (pins 14, 15, 18 and 19)	-0.7	V _P + 0.7	V
	input voltage (pins 27 and 28)	-0.1	+8.8	V
l _{av}	average current (pins 20, 22 and 24)	+4	-10	mA
I _M	peak current (pins 20, 22 and 24)	+4	-20	mA
I ₁₈	input current	0	2	mA
I ₂₆	output current	+0.5	-8	mA
T _{stg}	storage temperature	-20	+150	°C
T _{amb}	operating ambient temperature	0	70	°C
P _{tot}	total power dissipation			
	SOT117-1	_	1.2	W
	SOT261-2	_	1.0	W

CHARACTERISTICS

All voltages are measured in test circuit of Fig.10 with respect to GND (pin 9); $V_P = 8.0 \text{ V}$; $T_{amb} = 25 \text{ °C}$; nominal signal amplitudes (black-to-white) at output pins 24, 22 and 20; nominal settings of brightness, contrast, saturation and white level control; without beam current or peak drive limiting; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply (pin	5)			1	-	-1
VP	supply voltage		7.2	8.0	8.8	V
I _P	supply current		_	85	110	mA
Colour diffe	erence inputs [–(B – Y): pin 6; –(R – Y)	: pin 7]			,	
V _{6(p-p)}	–(B – Y) input (peak-to-peak value)	notes 1 and 2	-	1.33	-	V
V _{7(p-p)}	–(R – Y) signal (peak-to-peak value)	notes 1 and 2	_	1.05	-	V
V _{6,7}	internal DC bias voltage	at black level clamping	_	3.1	_	V
I _{6,7}	input current	during line scan	_	-	0.15	μA
		at black level clamping	100	-	-	μA
R _{6,7}	AC input resistance		10	-	_	MΩ
Luminance	/sync (VBS; Y: pin 8)					
V _{i(p-p)}	luminance input voltage at pin 8 (peak-to-peak value)	note 2	-	0.45	_	V
V _{8(bias)}	internal DC bias voltage	at black level clamping	-	3.1	-	V
I ₈	input current	during line scan	-	-	0.15	μA
		at black level clamping	100	-	_	μA
R ₈	AC input resistance		10	-	-	MΩ
RGB input	1 (R ₁ : pin 10; G ₁ : pin 11; B ₁ : pin 12)					
V _{i(p-p)}	input voltage at pins 10, 11 and 12 (peak-to-peak value)	note 2	-	0.7	-	V
V _{10/11/12(bias)}	internal DC bias voltage	at black level clamping	-	5.4	-	V
I _{10/11/12}	input current	during line scan	-	-	0.15	μA
		at black level clamping	100	-	-	μA
R _{10/11/12}	AC input resistance		10	-	-	MΩ
RGB input	2 (R ₂ : pin 2, G ₂ : pin 3, B ₂ : pin 4)					
V _{i(p-p)}	input voltage at pins 2, 3 and 4 (peak-to-peak value)	note 2	-	0.7	_	V
V _{2/3/4}	internal DC bias voltage	at black level clamping	-	5.4	-	V
I _{2/3/4}	input current	during line scan	-	-	0.15	μA
		at black level clamping	100	_	-	μA
R _{2/3/4}	AC input resistance		10	-	_	MΩ

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Fast signal	switch FSW_1 (pin 13) to select Y, CD o	r R ₁ , G ₁ , B ₁ inputs (con	trol bits: se	e Table 3)	-!	-1
V ₁₃	voltage to select Y and CD		-	_	0.4	V
	voltage range to select R ₁ , G ₁ , B ₁		0.9	_	5.0	V
R ₁₃	internal resistance to ground		_	4.0	-	kΩ
∆t	difference between transit times for signal switching and signal insertion		_	-	10	ns
Fast signal	switch FSW_2 (pin 1) to select Y, CD/R ₁	, G ₁ , B ₁ or R ₂ , G ₂ , B ₂ in	puts (cont	rol bits: se	e Table 3)	
V ₁	voltage to select Y, CD/R ₁ , G ₁ , B ₁		-	-	0.4	V
	voltage to select R ₂ , G ₂ , B ₂		0.9	_	5.0	V
₹ ₁	internal resistance to ground		_	4.0	-	kΩ
∆t	difference between transit times for signal switching and signal insertion		-	-	10	ns
•	-	at 2211		F		40
data byte 0 d _s	saturation below maximum	at 23H	_	5	_	dB
d _s Contrast ac maximum c	saturation below maximum ljust [acts on internal RGB signals und contrast); data byte 3FH for maximum	at 00H; f = 100 kHz der I ² C-bus control; sub		50 02H (bit r	- esolution	dB 1.5% o
d _s Contrast ac maximum c 00H for mir	saturation below maximum ljust [acts on internal RGB signals und contrast); data byte 3FH for maximum imum contrast]	at 00H; f = 100 kHz der I ² C-bus control; suk contrast, data byte 2CH		50 02H (bit ro nal contra	- esolution	dB 1.5% o
d _s Contrast ac maximum c	saturation below maximum ljust [acts on internal RGB signals und contrast); data byte 3FH for maximum	at 00H; f = 100 kHz der I ² C-bus control; sub		50 02H (bit r	- esolution	dB 1.5% o a byte
d _s Contrast ac maximum o 00H for mir d _c Brightness of brightne byte 00H fo	saturation below maximum ljust [acts on internal RGB signals und contrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals u ss range); data byte 3FH for maximum r minimum brightness]	at 00H; f = 100 kHz der l²C-bus control; sub contrast, data byte 2CH at 2CH at 00H under l²C-bus control; sub brightness, data byte 2	l for nomi – – sub-addre	50 02H (bit re nal contra 3 22 ss 00H (bit ominal brig	- esolution st and dat - - t resolutio	dB 1.5% o a byte dB dB on 1.5%
Contrast ac naximum c 00H for mir d _c Brightness of brightne oyte 00H fo	saturation below maximum ljust [acts on internal RGB signals undersontrast); data byte 3FH for maximum frimum contrast] contrast below maximum adjust [acts on internal RGB signals undersontrast] adjust [acts on internal RGB signals undersontrast] black level shift of nominal signal	at 00H; f = 100 kHz der l²C-bus control; sub contrast, data byte 2CH at 2CH at 00H under l²C-bus control; s brightness, data byte 2 at 3FH	l for nomi – – sub-addre	50 02H (bit renal contra 3 22 ss 00H (bit pminal brig 30	- esolution st and dat - - t resolutio	dB 1.5% o a byte dB dB on 1.5% nd data
d _s Contrast ac maximum o DOH for mir d _c Brightness of brightne byte 00H fo	saturation below maximum ljust [acts on internal RGB signals und contrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals u ss range); data byte 3FH for maximum r minimum brightness]	at 00H; f = 100 kHz der l²C-bus control; sub contrast, data byte 2CH at 2CH at 00H under l²C-bus control; sub brightness, data byte 2	l for nomi – sub-addre 27H for no	50 02H (bit re nal contra 3 22 ss 00H (bit ominal brig	- esolution st and dat - - t resolution ghtness ar	dB 1.5% c a byte dB dB on 1.5%
d _s Contrast ac maximum o 00H for mir d _c Brightness of brightne byte 00H fo d _{br}	saturation below maximum Ijust [acts on internal RGB signals und contrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals und ss range); data byte 3FH for maximum r minimum brightness] black level shift of nominal signal amplitude referred to cut-off	at 00H; f = 100 kHz der l²C-bus control; sub contrast, data byte 2CH at 2CH at 00H under l²C-bus control; sub brightness, data byte 2 at 3FH at 00H -addresses 04H (red), 0	l for nomi – sub-addre 27H for no – – – 5H (greer	50 02H (bit renal contra 3 22 ss 00H (bit ominal brig 30 -50 n) and 06H	- esolution st and dat - - t resolutio ghtness an - - (blue); da	dB 1.5% o a byte dB dB dB on 1.5% nd data % %
d _s Contrast ac maximum o DOH for mir d _c Brightness of brightne byte 00H fo d _{br} White poter 3FH for ma	saturation below maximum Ijust [acts on internal RGB signals underst]; data byte 3FH for maximum frimum contrast] contrast below maximum adjust [acts on internal RGB signals underst]; data byte 3FH for maximum adjust [acts on internal RGB signals underst]; data byte 3FH for maximum adjust [acts on internal RGB signals underst] black level shift of nominal signal amplitude referred to cut-off measurement level ntiometers [under I²C-bus control; substance	at 00H; f = 100 kHz der l²C-bus control; sub contrast, data byte 2CH at 2CH at 00H under l²C-bus control; sub brightness, data byte 2 at 3FH at 00H -addresses 04H (red), 0	l for nomi – sub-addre 27H for no – – – 5H (greer	50 02H (bit renal contra 3 22 ss 00H (bit ominal brig 30 -50 n) and 06H	- esolution st and dat - - t resolutio ghtness an - - (blue); da	dB 1.5% of a byte dB dB dB on 1.5% nd data % %
d _s Contrast ac maximum o 00H for mir d _c Brightness of brightne byte 00H fo d _{br}	saturation below maximum Ijust [acts on internal RGB signals undersontrast); data byte 3FH for maximum frimum contrast] contrast below maximum adjust [acts on internal RGB signals undersontrast] contrast below maximum adjust [acts on internal RGB signals undersontrast] black level solution below maximum brightness] black level shift of nominal signal amplitude referred to cut-off measurement level ntiometers [under I²C-bus control; sub ximum gain; data byte 22H for nominal	at 00H; f = 100 kHz der l²C-bus control; sub contrast, data byte 2CH at 2CH at 00H under l²C-bus control; sub brightness, data byte 2 at 3FH at 00H -addresses 04H (red), 0	l for nomi – sub-addre 27H for no – – – 5H (greer	50 02H (bit renal contra 3 22 ss 00H (bit ominal brig 30 -50 n) and 06H	- esolution st and dat - - t resolutio ghtness an - - (blue); da	dB 1.5% of a byte dB dB dB on 1.5% nd data % %

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
•	ts (pins 24, 22 and 20; positive going o	output signals and no p	eak drive	limitation	;	1
sub-addres	s 0AH = 3FH); note 4			-		
V _{o(b-w)}	nominal output signals (black-to-white value)		-	2.0	D – C	
	maximum output signals (black-to-white value)		3.2	-	-	V
ΔV_o	spread between RGB output signals		-	-	10	%
Vo	output voltages		6.8	-	0.8	V
V _{24,22,20}	voltage of cut-off measurement line	output clamping (BCOF = 1)	2.3	2.5	2.7	V
l _{int}	internal current sources		-	5.0	-	mA
R _o	output resistance		_	65	110	Ω
Frequency	response					
d	frequency response of Y path (from pin 8 to pins 24, 22, 20)	f = 10 MHz	-	-	3	dB
	frequency response of CD path (from pins 7 to 24 and 6 to 20)	f = 8 MHz	-	-	3	dB
	frequency response of RGB ₁ path (from pins 10 to 24, 11 to 22 and 12 to 20)	f = 10 MHz	-	-	3	dB
	frequency response of RGB_2 path (from pins 2 to 24, 3 to 22 and 4 to 20)	f = 10 MHz	-	_	3	dB
Sandcastle	pulse detector (pin 14)					
CONTROL BIT	SC5 = 0; 3-LEVEL; notes 5 and 6					
V ₁₄	sandcastle pulse voltage					
	for horizontal and vertical blanking pulses		2.0	2.5	3.0	V
	for horizontal pulses (line count)		4.0	4.5	5.0	V
	for burst key pulses		6.3	-	V _P + 0.7	V
CONTROL BIT	SC5 = 1; 2-LEVEL; note 5			-		
V ₁₄	sandcastle pulse voltage					
	for horizontal and vertical blanking pulses		2.0	2.5	3.0	V
	for burst key pulses		4.0	4.5	V _P + 0.7	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
GENERAL		1				-1
I ₁₄	input current	V ₁₄ < 0.5 V	-100	-	-	μA
t _d	leading edge delay of the clamping	control bit DELOF = 0	_	1.5	_	μs
	pulse	control bit DELOF = 1	_	0	_	μs
t _{BK}	required burst key pulse time	control bit DELOF = 0; normally used with f_L	3	-	_	μs
		control bit DELOF = 1; normally used with $2f_L$	1.5	_	_	μs
n _{pulse}	required horizontal or burst key pulses during vertical blanking interval	e.g. at interlace scan (VBW2 = 0)	4	_	29	-
		e.g. at progressive line scan (VBW2 = 1)	8	_	57	-
Average be	am current limiting (pin 15); note 7				·	
V _{c(15)}	contrast reduction starting voltage		-	4.0	-	V
$\Delta V_{c(15)}$	voltage difference for full contrast reduction		-	-2.0	_	V
V _{br(15)}	brightness reduction starting voltage		-	2.5	_	V
$\Delta V_{br(15)}$	voltage difference for full brightness reduction		-	-1.6	-	V
	limiting voltage [pin 16; internal peak o b-address 0AH]; note 8	drive limiting level (V _{pdl})	acts on I	RGB outp	uts under	l²C-bus
V _{20/22/24}	RGB output voltages	at 00H	_	-	3.0	V
		at 3FH	6.5	-	_	V
I ₁₆	charge current		_	-1	_	μA
	discharge current	during peak white	_	5	_	mA
V ₁₆	internal voltage limitation		4.5	-	_	V
V _{c(16)}	contrast reduction starting voltage		-	4.0	_	V
$\Delta V_{c(16)}$	voltage difference for full contrast reduction		-	-2.0	-	V
V _{br(16)}	brightness reduction starting voltage		-	2.5	_	V
ΔV _{br(16)}	voltage difference for full brightness reduction		-	-1.6	-	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Automatic of	cut-off and white level control (pins 19	and 18); notes 9 to 11; see	e Fig.8	-		
V ₁₉	permissible voltage (also during scanning period)		-	-	V _P – 1.4	V
I ₁₉	output current		-	-	-140	μA
	input current		150	-	-	μA
	additional input current	only during warming up	-	0.5	-	mA
V _{24,22,20}	warming up amplitude (under I ² C-bus control; sub-address 0AH)	switch-on delay 1	-	$V_{pdl} - 0.7$	-	V
V _{19(th)}	voltage threshold for picture tube cathode warming up	switch-on delay 1	-	5.0	-	V
V _{ref}	internally controlled voltage	during leakage measurement period	-	3.0	-	V
DATA BYTE 0 REFERENCE I	7H FOR RED REFERENCE LEVEL, DATA BYTE LEVEL	08H FOR GREEN REFERENCE	E LEVEL	AND DATA BY	те 09H FC	R BLUE
ΔV_{19}	difference between V _{MEAS} (cut-off or	3FH (maximum V _{MEAS})	1.5	-	-	V
	white level measurement voltage) and	20H (nominal V _{MEAS})	-	1.0	-	V
	V _{ref}	00H (minimum V _{MEAS})	-	-	0.5	V
I ₁₈	input current	white level measurement	-	-	800	μA
R ₁₈	internal resistance	to V_{ref} ; $I_{18} \le 800 \ \mu A$	-	100	-	Ω
ΔV_{19}	white level register (measured value within tolerance range)	white level measurement	-	250	-	mV
Storage of	cut-off control voltage/output clamping	g voltage (pins 25, 23 and	21)			
I _{21/23/25}	charge and discharge currents	during cut-off measurement lines	- 0.3 -		-	mA
	input currents of storage inputs	outside measurement time	-	-	0.1	μA
Storage of I	eakage information (pin 17)					
I ₁₇	charge and discharge currents	during leakage measurement period	-	0.4	-	mA
	leakage current	outside time LM	-	-	0.1	μA
V ₁₇	voltage for reset to switch-on below		_	-	3.0	V
	l (under I ² C-bus control; sub-address (Itage and data byte 00H for minimum v		aximum	n voltage; d	ata byte 2	0H for
V ₂₆	output voltage	at 3FH	4.8	-	_	V
-		at 20H	_	3.0	_	V
		at 00H	_	-	1.0	V
l _{int}	current of the internal current source at pin 26		500	-	-	μA

TDA4680

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I ² C-bus tran	sceiver clock SCL (pin 28)		Į	l	-	-
f _{SCL}	input frequency range		0	_	100	kHz
V _{IL}	LOW level input voltage		_	_	1.5	V
V _{IH}	HIGH level input voltage		3.0	_	6.0	V
IIL	LOW level input current	V ₂₈ = 0.4 V	-10	_	-	μA
I _{IH}	HIGH level input current		_	_	10	μA
tL	clock pulse LOW		4.7	-	-	μs
t _H	clock pulse HIGH		4.0	_	-	μs
t _r	rise time		-	-	1.0	μs
t _f	fall time		_	-	0.3	μs
I ² C-bus tran	sceiver data input/output SDA (pir	n 27)				
V _{IL}	LOW level input voltage		-	-	1.5	V
V _{IH}	HIGH level input voltage		3.0	_	6.0	V
IIL	LOW level input current	V ₂₇ = 0.4 V	-10	_	-	μA
I _{IH}	HIGH level input current		_	_	10	μA
I _{OL}	LOW level output current	V ₂₇ = 0.4 V	3.0	_	-	mA
t _r	rise time		_	_	1.0	μs
t _f	fall time		_	_	0.3	μs
t _{SU;DAT}	data set-up time		0.25	_	-	μs

Notes to the characteristics

- 1. The values of the -(B Y) and -(R Y) colour difference input signals are for a 75% colour-bar signal.
- 2. The pins are capacitively coupled to a low ohmic source, with a recommended maximum output impedance of 600 Ω.
- 3. The white potentiometers affect the amplitudes of the RGB output signals including the white measurement pulses.
- 4. The RGB outputs at pins 24, 22 and 20 are emitter followers with current sources.
- Sandcastle pulses are compared with internal threshold voltages independent of V_P. The threshold voltages separate the components of the sandcastle pulse. The particular component is generated when the voltage on pin 14 exceeds the defined internal threshold voltage.

The internal threshold voltages (control bit SC5 = 0) are:

- 1.5 V for horizontal and vertical blanking pulses
- 3.5 V for horizontal pulses
- 6.0 V for the burst key pulse.

The internal threshold voltages (control bit SC5 = 1) are:

1.5 V for horizontal and vertical blanking pulses

3.5 V for the burst key pulse.

- 6. A sandcastle pulse with a maximum voltage equal to $(V_P + 0.7 V)$ is obtained by limiting a 12 V sandcastle pulse.
- 7. Average beam current limiting reduces the contrast, at minimum contrast it reduces the brightness.
- Peak drive limiting reduces the RGB outputs by reducing the contrast, at minimum contrast it reduces the brightness. The maximum RGB outputs are determined via the I²C-bus under sub-address 0AH. When an RGB output exceeds the maximum voltage, peak drive limiting is delayed by one horizontal line.

TDA4680

- 9. The vertical blanking interval is defined by a vertical pulse which contains 4 (8) or more horizontal pulses; it begins with the start of the vertical pulse and ends with the end of the white measuring line. If the vertical pulse is longer than the selected vertical blanking window the blanking period ends with the end of the complete line after the end of the vertical pulse. The counter cycle time is 31 (63) horizontal pulses. If the vertical pulse contains more than 29 (57) horizontal pulses, the black level storage capacitors will be discharged while all signals are blanked. During leakage current measurement, the RGB channels are blanked to ultra-black level. During cut-off measurement one channel is set to the measurement pulse level, the other channels are blanked to ultra-black. Since the brightness adjust shifts the colour signal relative to the black level, the brightness adjust is disabled during the vertical blanking interval (see Figs 7 and 8).
- 10. During picture cathode warming up (first switch-on delay) the RGB outputs (pins 24, 22 and 20) are blanked to the ultra-black level during line scan. During the vertical blanking interval a white-level monitor pulse is fed out on the RGB outputs and the cathode currents are measured. When the voltage threshold on pin 19 is greater than 5.0 V, the monitor pulse is switched off and cut-off and white level control are activated (second switch-on delay). As soon as cut-off control stabilizes, RGB output blanking is removed.
- 11. Range of cut-off measurement level at the RGB outputs is 1 to 5 V. The recommended value is 3 V.
- 12. The hue control output at pin 26 is an emitter follower with current source.

Table 5	Demodulator	axes and an	plification factors

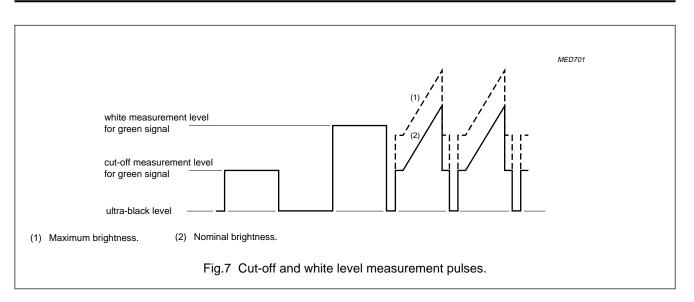
PARAMETER	NTSC	PAL
(B – Y)* demodulator axis	0°	0°
(R – Y)* demodulator axis	115°	90°
(R – Y)* amplification factor	1.97	1.14
(B – Y)* amplification factor	2.03	2.03

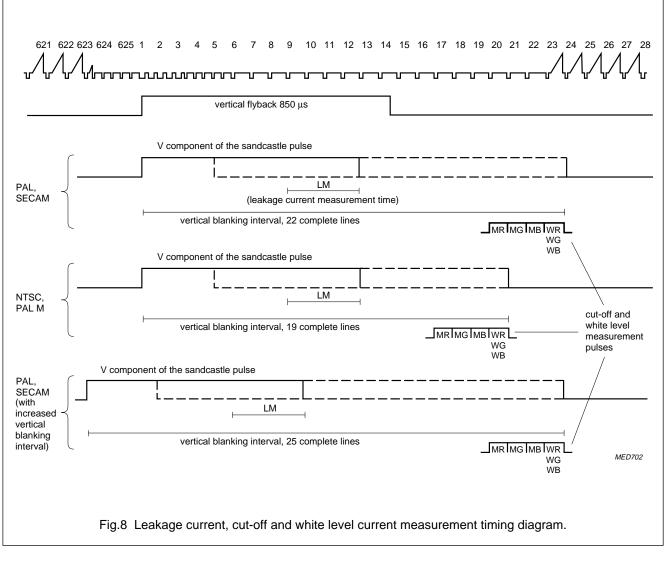
Table 6	PAL/SECAM and NTSC matrix; notes 1 and 2
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MATRIX	NMEN
PAL/SECAM	0
NTSC	1

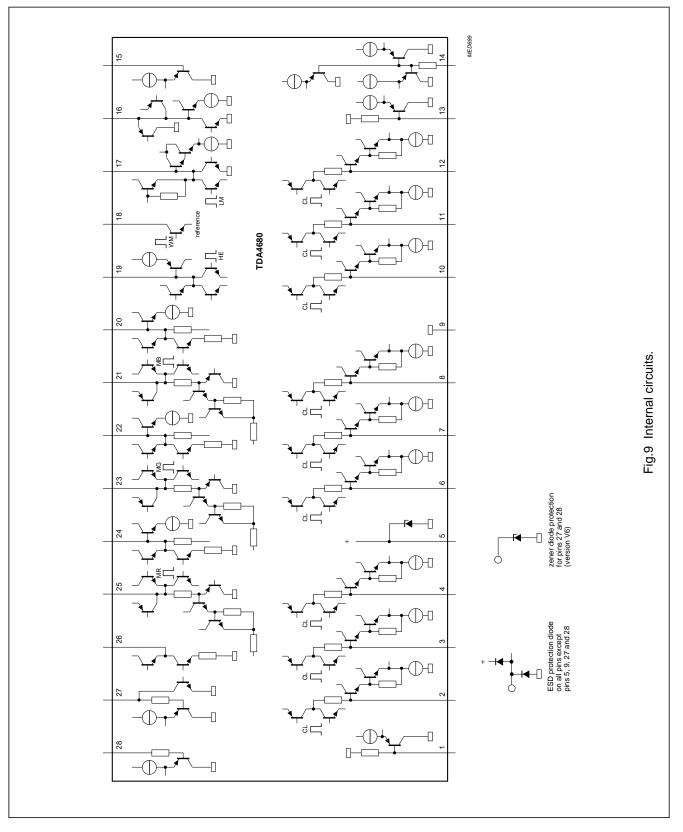
Notes

- PAL/SECAM signals are matrixed by the equation: V_{G-Y} = -0.51V_{R-Y} 0.19V_{B-Y} NTSC signals are matrixed by the equations (hue phase shift of -5 degrees): V_{R-Y*} = 1.57V_{R-Y} - 0.41V_{B-Y}; V_{G-Y*} = -0.43V_{R-Y} - 0.11V_{B-Y}; V_{B-Y*} = V_{B-Y} In the matrix equations: V_{R-Y} and V_{B-Y} are conventional PAL demodulation axes and amplitudes at the output of the NTSC demodulator. V_{G-Y*}, V_{R-Y*} and V_{B-Y*} are the NTSC-modified colour difference signals; this is equivalent to the demodulator axes and amplification factors shown in Table 5. V_{G-Y*} = -0.27V_{R-Y*} - 0.22V_{B-Y*}.
- 2. The vertical blanking interval is selected via the l²C-bus (see Table 2 and Fig.8). Vertical blanking is determined by the vertical component of the sandcastle pulse; this vertical component has priority when it is longer than the vertical blanking interval of the transmission standard.

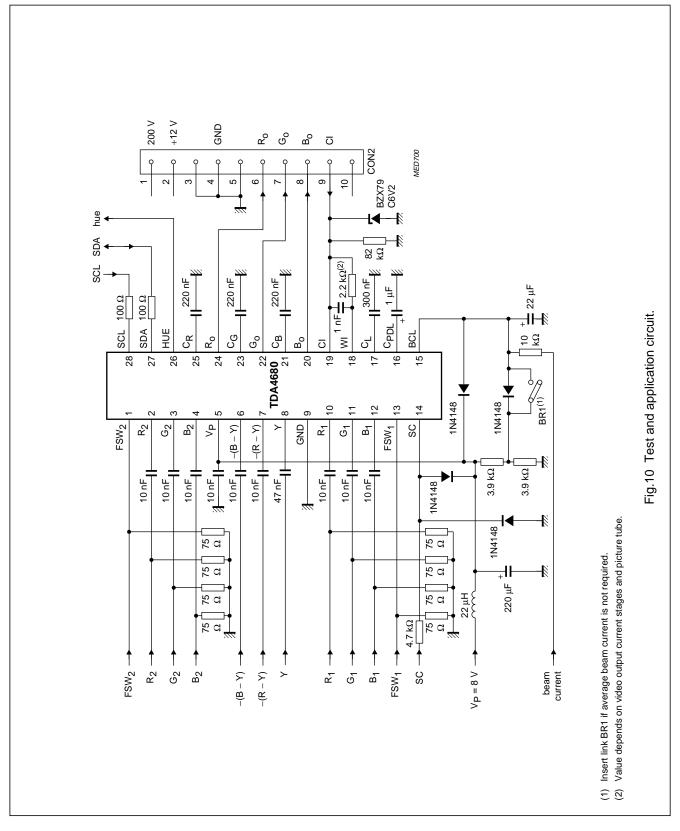




INTERNAL PIN CONFIGURATION

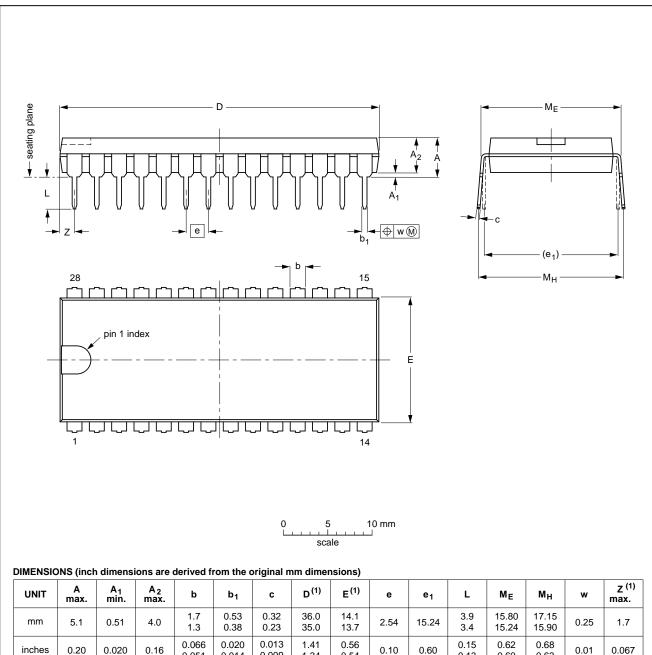






PACKAGE OUTLINES

DIP28: plastic dual in-line package; 28 leads (600 mil)



Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

0.051

0.014

0.009

OUTLINE		REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT117-1	051G05	MO-015AH				-92-11-17 95-01-14	

0.54

0.13

0.60

0.63

1.34

TDA4680

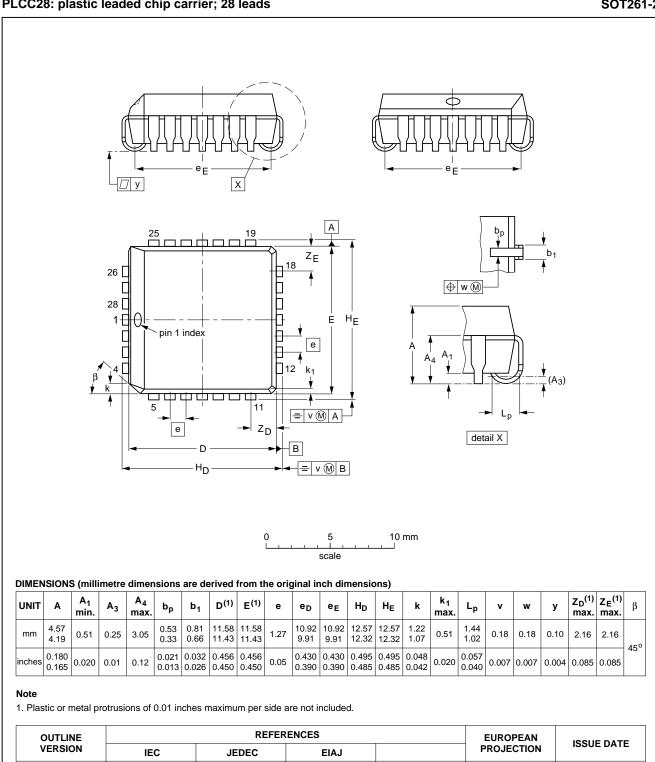
SOT117-1

TDA4680

92-11-17

95-02-25

 \square



PLCC28: plastic leaded chip carrier; 28 leads

SOT261-2

SOT261-2

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

PLCC

REFLOW SOLDERING

Reflow soldering techniques are suitable for all PLCC packages.

The choice of heating method may be influenced by larger PLCC packages (44 leads, or more). If infrared or vapour phase heating is used and the large packages are not absolutely dry (less than 0.1% moisture content by weight), vaporization of the small amount of moisture in them can cause cracking of the plastic body. For more information, refer to the Drypack chapter in our *"Quality Reference Handbook"* (order code 9397 750 00192).

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 $^{\circ}$ C.

WAVE SOLDERING

Wave soldering techniques can be used for all PLCC packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

TDA4680

DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.					
Application information					
Where application informati	on is given, it is advisory and does not form part of the specification.				

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

PURCHASE OF PHILIPS I²C COMPONENTS



Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

Product specification

Video processor with automatic cut-off and white level control

TDA4680

NOTES

Product specification

Video processor with automatic cut-off and white level control

TDA4680

NOTES

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